

Title (en)  
INTEGRATED CIRCUITS WITH CONTACT PADS IN A STANDARD ARRAY.

Title (de)  
INTEGRIERTE SCHALTUNGEN MIT ANSCHLUSSKONTAKTEN IN EINER STANDARDORDNUNG.

Title (fr)  
CIRCUITS INTEGRES MUNIS DE PLOTS DE CONTACT DANS UN RESEAU STANDARD.

Publication  
**EP 0179802 A1 19860507 (EN)**

Application  
**EP 85901784 A 19850319**

Priority  
US 59218684 A 19840322

Abstract (en)  
[origin: WO8504518A1] An integrated circuit chip (310) includes a top layer of dielectric (320) penetrated by conductive vias (305) connecting electrical contacts (304) within the integrated circuit proper to a network of electrical leads (326) disposed on top of the dielectric layer (320); the network of leads (326), in turn, being connected to an array of contact pads (330) adapted for simultaneous solder connection to a leadframe.

Abstract (fr)  
Une puce à circuits intégrés (310) comprend une couche supérieure de diélectrique (320) dans laquelle pénètrent des conducteurs (305) reliant les contacts électriques (304) dans le circuit intégré proprement dit à un réseau de conducteurs électriques (326) disposés au sommet de la couche diélectrique (320); le réseau de conducteurs (326) est relié à son tour à un réseau de plots de contact (330) adaptés à la connexion simultanée par soudage à un cadre conducteur.

IPC 1-7  
**H01L 21/92**; **H01L 23/50**

IPC 8 full level  
**H01L 21/60** (2006.01); **H01L 23/485** (2006.01); **H01L 25/16** (2006.01)

CPC (source: EP KR)  
**H01L 21/60** (2021.08 - KR); **H01L 24/05** (2013.01 - EP); **H01L 24/18** (2013.01 - EP); **H01L 24/82** (2013.01 - EP); **H01L 24/97** (2013.01 - EP); **H01L 25/16** (2013.01 - EP); **H01L 24/45** (2013.01 - EP); **H01L 2223/5448** (2013.01 - EP); **H01L 2224/0401** (2013.01 - EP); **H01L 2224/05599** (2013.01 - EP); **H01L 2224/16** (2013.01 - EP); **H01L 2224/16227** (2013.01 - EP); **H01L 2224/18** (2013.01 - EP); **H01L 2224/45124** (2013.01 - EP); **H01L 2224/45144** (2013.01 - EP); **H01L 2224/97** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/01005** (2013.01 - EP); **H01L 2924/01006** (2013.01 - EP); **H01L 2924/01009** (2013.01 - EP); **H01L 2924/01013** (2013.01 - EP); **H01L 2924/01014** (2013.01 - EP); **H01L 2924/01015** (2013.01 - EP); **H01L 2924/01019** (2013.01 - EP); **H01L 2924/01022** (2013.01 - EP); **H01L 2924/01023** (2013.01 - EP); **H01L 2924/01027** (2013.01 - EP); **H01L 2924/01029** (2013.01 - EP); **H01L 2924/0103** (2013.01 - EP); **H01L 2924/01033** (2013.01 - EP); **H01L 2924/01039** (2013.01 - EP); **H01L 2924/01047** (2013.01 - EP); **H01L 2924/0105** (2013.01 - EP); **H01L 2924/01055** (2013.01 - EP); **H01L 2924/01074** (2013.01 - EP); **H01L 2924/01075** (2013.01 - EP); **H01L 2924/01078** (2013.01 - EP); **H01L 2924/01079** (2013.01 - EP); **H01L 2924/01082** (2013.01 - EP); **H01L 2924/01322** (2013.01 - EP); **H01L 2924/014** (2013.01 - EP); **H01L 2924/10253** (2013.01 - EP); **H01L 2924/13091** (2013.01 - EP); **H01L 2924/14** (2013.01 - EP); **H01L 2924/15787** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP); **H01L 2924/19041** (2013.01 - EP); **H01L 2924/19042** (2013.01 - EP); **H01L 2924/19043** (2013.01 - EP); **H01L 2924/30107** (2013.01 - EP); **H01L 2924/3011** (2013.01 - EP)

C-Set (source: EP)  
1. **H01L 2224/45124 + H01L 2924/00014**  
2. **H01L 2224/45124 + H01L 2924/00015**  
3. **H01L 2924/181 + H01L 2924/00**  
4. **H01L 2224/45144 + H01L 2924/00014**  
5. **H01L 2224/97 + H01L 2224/82**  
6. **H01L 2924/00014 + H01L 2224/05599**  
7. **H01L 2924/10253 + H01L 2924/00**  
8. **H01L 2924/00014 + H01L 2224/48**  
9. **H01L 2924/15787 + H01L 2924/00**  
10. **H01L 2224/45144 + H01L 2924/00015**  
11. **H01L 2924/00014 + H01L 2224/85399**

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